

# MC74HCT86A

## Quad 2-Input Exclusive OR Gate with LSTTL Compatible Inputs

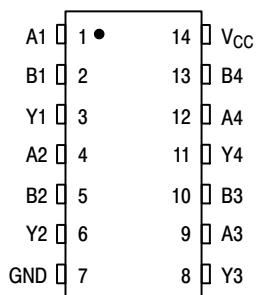
### High-Performance Silicon-Gate CMOS

The MC74HCT86A is identical in pinout to the LS86. The device inputs are compatible with standard CMOS outputs and LSTTL outputs.

#### Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1  $\mu$ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with JEDEC Standard No. 7A Requirements
- Chip Complexity: 56 FETs or 14 Equivalent Gates
- These are Pb-Free Devices

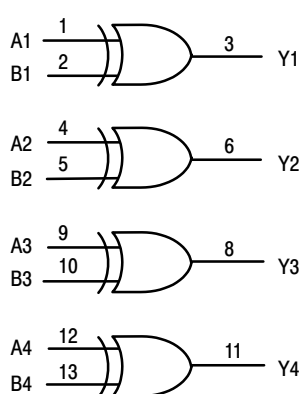
#### PIN ASSIGNMENT



#### FUNCTION TABLE

| Inputs |   | Output |
|--------|---|--------|
| A      | B | Y      |
| L      | L | L      |
| L      | H | H      |
| H      | L | H      |
| H      | H | L      |

#### LOGIC DIAGRAM



$$Y = A \oplus B$$

$$= \bar{A}B + A\bar{B}$$

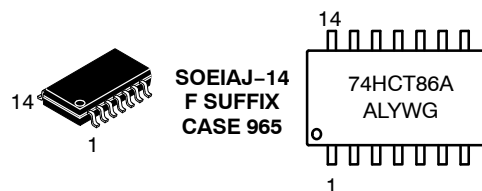
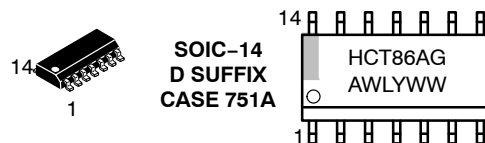
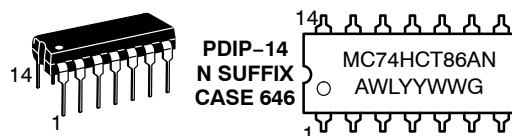
PIN 14 =  $V_{CC}$   
PIN 7 = GND



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#### MARKING DIAGRAMS



A = Assembly Location  
L, WL = Wafer Lot  
Y, YY = Year  
W, WW = Work Week  
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

# MC74HCT86A

## MAXIMUM RATINGS

| Symbol    | Parameter                                                                               | Value                   | Unit |
|-----------|-----------------------------------------------------------------------------------------|-------------------------|------|
| $V_{CC}$  | DC Supply Voltage (Referenced to GND)                                                   | – 0.5 to + 7.0          | V    |
| $V_{in}$  | DC Input Voltage (Referenced to GND)                                                    | – 0.5 to $V_{CC} + 0.5$ | V    |
| $V_{out}$ | DC Output Voltage (Referenced to GND)                                                   | – 0.5 to $V_{CC} + 0.5$ | V    |
| $I_{in}$  | DC Input Current, per Pin                                                               | $\pm 20$                | mA   |
| $I_{out}$ | DC Output Current, per Pin                                                              | $\pm 25$                | mA   |
| $I_{CC}$  | DC Supply Current, $V_{CC}$ and GND Pins                                                | $\pm 50$                | mA   |
| $P_D$     | Power Dissipation in Still Air,<br>Plastic DIP†<br>SOIC Package†<br>TSSOP Package†      | 750<br>500<br>450       | mW   |
| $T_{stg}$ | Storage Temperature                                                                     | – 65 to + 150           | °C   |
| $T_L$     | Lead Temperature, 1 mm from Case for 10 Seconds<br>(Plastic DIP, SOIC or TSSOP Package) | 260                     | °C   |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Derating — Plastic DIP: – 10 mW/°C from 65° to 125°C  
SOIC Package: – 7 mW/°C from 65° to 125°C  
TSSOP Package: – 6.1 mW/°C from 65° to 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $GND \leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$ . Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

## RECOMMENDED OPERATING CONDITIONS

| Symbol                             | Parameter                                            | Min                                                                           | Max                     | Unit |
|------------------------------------|------------------------------------------------------|-------------------------------------------------------------------------------|-------------------------|------|
| V <sub>CC</sub>                    | DC Supply Voltage (Referenced to GND)                | 2.0                                                                           | 6.0                     | V    |
| V <sub>in</sub> , V <sub>out</sub> | DC Input Voltage, Output Voltage (Referenced to GND) | 0                                                                             | V <sub>CC</sub>         | V    |
| T <sub>A</sub>                     | Operating Temperature, All Package Types             | − 55                                                                          | + 125                   | °C   |
| t <sub>r</sub> , t <sub>f</sub>    | Input Rise and Fall Time<br>(Figure 1)               | V <sub>CC</sub> = 2.0 V<br>V <sub>CC</sub> = 4.5 V<br>V <sub>CC</sub> = 6.0 V | 0<br>1000<br>500<br>400 | ns   |

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## DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

| Symbol          | Parameter                                      | Test Conditions                                                                     | V <sub>CC</sub><br>V | Guaranteed Limit |            |            | Unit |
|-----------------|------------------------------------------------|-------------------------------------------------------------------------------------|----------------------|------------------|------------|------------|------|
|                 |                                                |                                                                                     |                      | – 55 to 25°C     | ≤ 85°C     | ≤ 125°C    |      |
| V <sub>IH</sub> | Minimum High-Level Input Voltage               | V <sub>out</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V<br> I <sub>out</sub>   ≤ 20 μA  | 4.5 to 5.5           | 2.0              | 2.0        | 2.0        | V    |
| V <sub>IL</sub> | Maximum Low-Level Input Voltage                | V <sub>out</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V<br> I <sub>out</sub>   ≤ 20 μA  | 4.5 to 5.5           | 0.8              | 0.8        | 0.8        | V    |
| V <sub>OH</sub> | Minimum High-Level Output Voltage              | V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub><br> I <sub>out</sub>   ≤ 20 μA | 4.5 to 5.5           | 4.4 to 5.4       | 4.4 to 5.4 | 4.4 to 5.4 | V    |
|                 |                                                | V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub>  I <sub>out</sub>   ≤ 4.0 mA   | 4.5                  | 3.98             | 3.84       | 3.70       |      |
| V <sub>OL</sub> | Maximum Low-Level Output Voltage               | V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub><br> I <sub>out</sub>   ≤ 20 μA | 4.5 to 5.5           | 0.1 to 0.1       | 0.1 to 0.1 | 0.1 to 0.1 | V    |
|                 |                                                | V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub>  I <sub>out</sub>   ≤ 4.0 mA   | 4.5                  | 0.26             | 0.33       | 0.40       |      |
| I <sub>in</sub> | Maximum Input Leakage Current                  | V <sub>in</sub> = V <sub>CC</sub> or GND                                            | 5.5                  | ± 0.1            | ± 1.0      | ± 1.0      | μA   |
| I <sub>CC</sub> | Maximum Quiescent Supply Current (per Package) | V <sub>in</sub> = V <sub>CC</sub> or GND<br>I <sub>out</sub> = 0 μA                 | 5.5                  | 1.0              | 10         | 40         | μA   |

## AC ELECTRICAL CHARACTERISTICS (C<sub>L</sub> = 50 pF, Input t<sub>r</sub> = t<sub>f</sub> = 6 ns, V<sub>CC</sub> = 5.0 V ± 10%)

| Symbol                                 | Parameter                                                                | V <sub>CC</sub><br>V                               | Guaranteed Limit |          |          | Unit |
|----------------------------------------|--------------------------------------------------------------------------|----------------------------------------------------|------------------|----------|----------|------|
|                                        |                                                                          |                                                    | – 55 to 25°C     | ≤ 85°C   | ≤ 125°C  |      |
| t <sub>PLH</sub> ,<br>t <sub>PHL</sub> | Maximum Propagation Delay, Input A or B to Output Y<br>(Figures 1 and 2) | t <sub>PLH</sub><br>5.0<br>t <sub>PHL</sub><br>5.0 | 20<br>17         | 25<br>21 | 31<br>26 | ns   |
| t <sub>TLH</sub> ,<br>t <sub>THL</sub> | Maximum Output Transition Time, Any Output<br>(Figures 1 and 2)          | 5.0                                                | 15               | 19       | 22       | ns   |
| C <sub>in</sub>                        | Maximum Input Capacitance                                                | —                                                  | 10               | 10       | 10       | pF   |
| C <sub>PD</sub>                        | Power Dissipation Capacitance (Per Gate)*                                | Typical @ 25°C, V <sub>CC</sub> = 5.0 V            |                  |          |          | pF   |
|                                        |                                                                          | 33                                                 |                  |          |          |      |

\*Used to determine the no-load dynamic power consumption: P<sub>D</sub> = C<sub>PD</sub> V<sub>CC</sub><sup>2</sup>f + I<sub>CC</sub> V<sub>CC</sub>.

## ORDERING INFORMATION

| Device          | Package                | Shipping†          |
|-----------------|------------------------|--------------------|
| MC74HCT86ANG    | PDIP–14<br>(Pb–Free)   | 25 Units / Rail    |
| MC74HCT86ADG    | SOIC–14<br>(Pb–Free)   | 55 Units / Rail    |
| MC74HCT86ADR2G  | SOIC–14<br>(Pb–Free)   | 2500 / Tape & Reel |
| MC74HCT86ADTR2G | TSSOP–14*              |                    |
| MC74HCT86AFG    | SOEIAJ–14<br>(Pb–Free) | 50 Units / Rail    |
| MC74HCT86AFELG  | SOEIAJ–14<br>(Pb–Free) | 2000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*This package is inherently Pb–Free.

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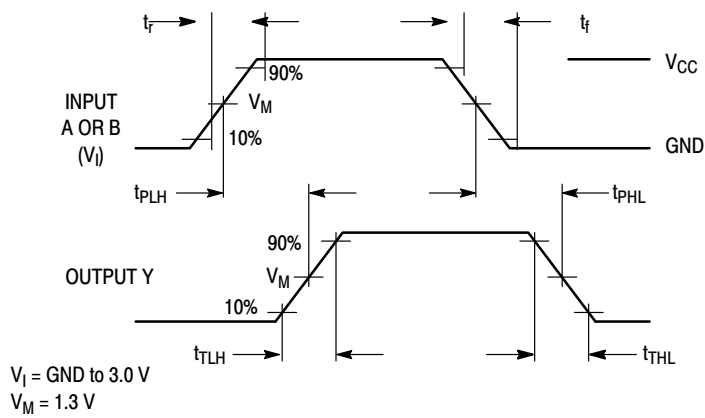


Figure 1. Switching Waveforms

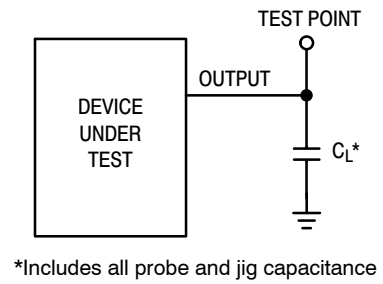


Figure 2. Test Circuit

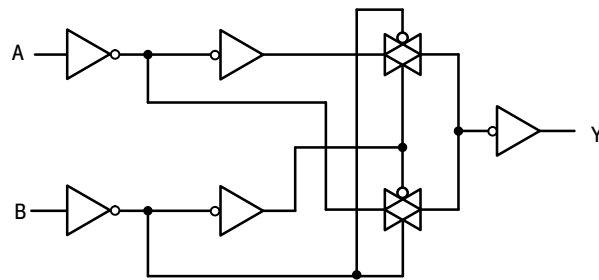
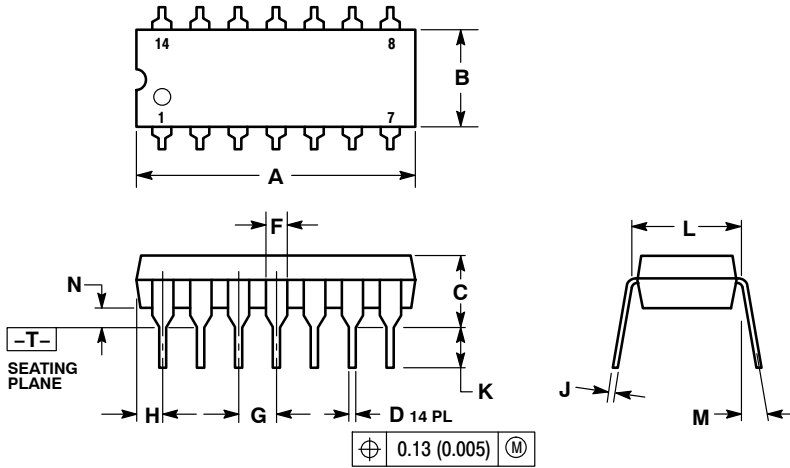


Figure 3. Expanded Logic Diagram  
(1/4 of Device)

# MC74HCT86A

## PACKAGE DIMENSIONS

PDIP-14  
CASE 646-06  
ISSUE P



### NOTES:

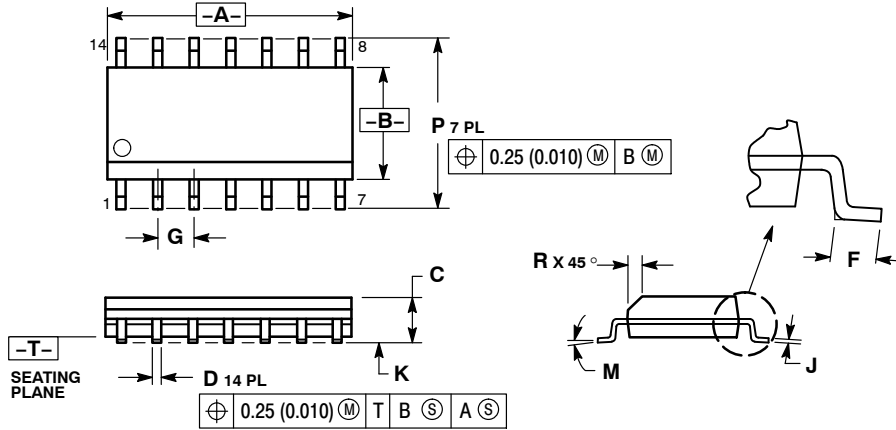
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

| DIM | INCHES    |       | MILLIMETERS |       |
|-----|-----------|-------|-------------|-------|
|     | MIN       | MAX   | MIN         | MAX   |
| A   | 0.715     | 0.770 | 18.16       | 19.56 |
| B   | 0.240     | 0.260 | 6.10        | 6.60  |
| C   | 0.145     | 0.185 | 3.69        | 4.69  |
| D   | 0.015     | 0.021 | 0.38        | 0.53  |
| F   | 0.040     | 0.070 | 1.02        | 1.78  |
| G   | 0.100 BSC |       | 2.54 BSC    |       |
| H   | 0.052     | 0.095 | 1.32        | 2.41  |
| J   | 0.008     | 0.015 | 0.20        | 0.38  |
| K   | 0.115     | 0.135 | 2.92        | 3.43  |
| L   | 0.290     | 0.310 | 7.37        | 7.87  |
| M   | 10 °      |       | 10 °        |       |
| N   | 0.015     | 0.039 | 0.38        | 1.01  |

# MC74HCT86A

## PACKAGE DIMENSIONS

SOIC-14  
CASE 751A-03  
ISSUE J

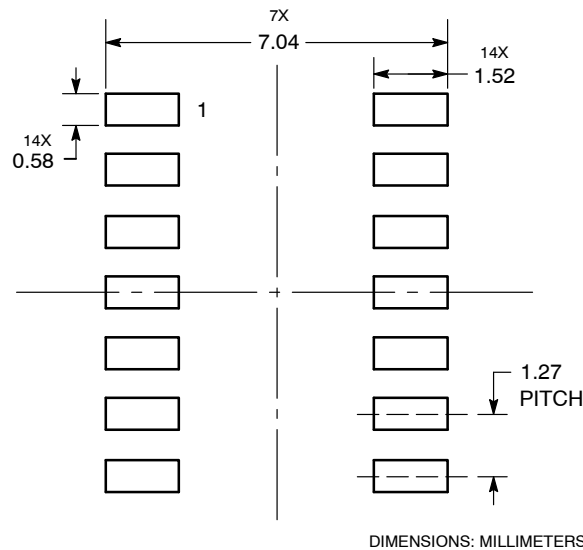


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| DIM | MILLIMETERS |      | INCHES    |       |
|-----|-------------|------|-----------|-------|
|     | MIN         | MAX  | MIN       | MAX   |
| A   | 8.55        | 8.75 | 0.337     | 0.344 |
| B   | 3.80        | 4.00 | 0.150     | 0.157 |
| C   | 1.35        | 1.75 | 0.054     | 0.068 |
| D   | 0.35        | 0.49 | 0.014     | 0.019 |
| F   | 0.40        | 1.25 | 0.016     | 0.049 |
| G   | 1.27 BSC    |      | 0.050 BSC |       |
| J   | 0.19        | 0.25 | 0.008     | 0.009 |
| K   | 0.10        | 0.25 | 0.004     | 0.009 |
| M   | 0°          | 7°   | 0°        | 7°    |
| P   | 5.80        | 6.20 | 0.228     | 0.244 |
| R   | 0.25        | 0.50 | 0.010     | 0.019 |

### SOLDERING FOOTPRINT\*

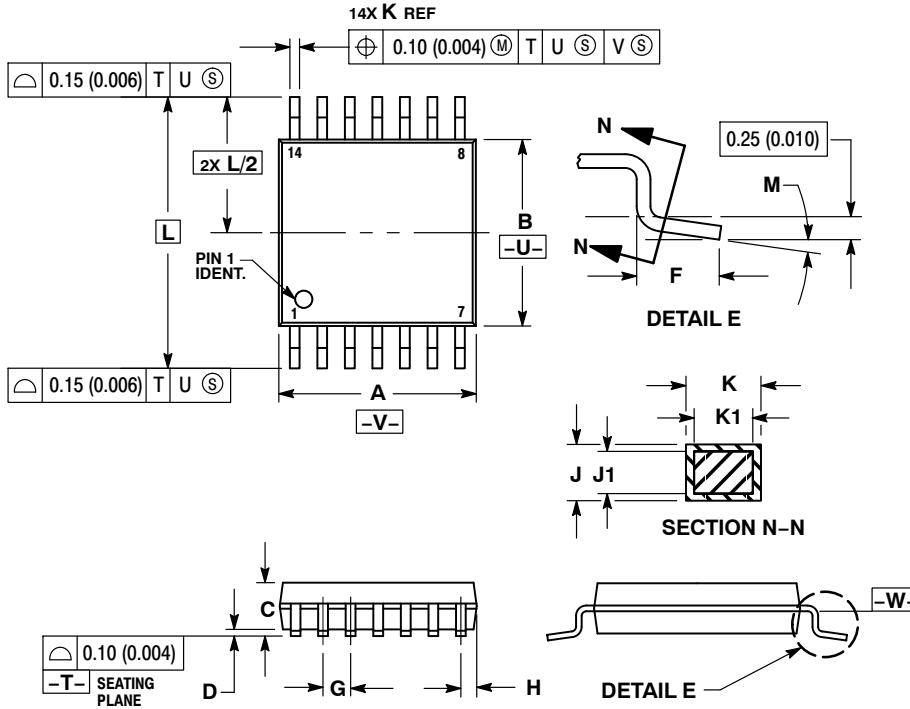


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC74HCT86A

## PACKAGE DIMENSIONS

TSSOP-14  
CASE 948G-01  
ISSUE B

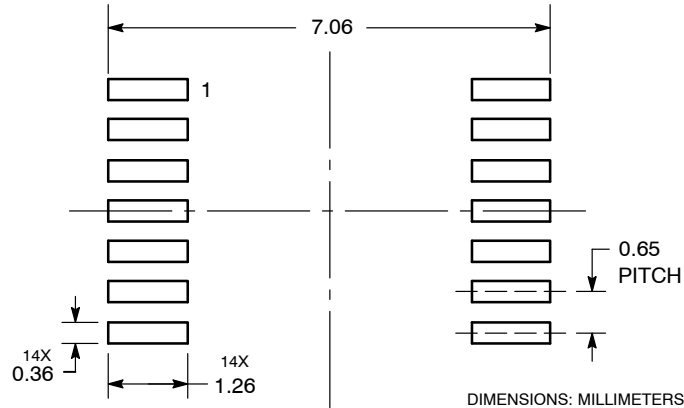


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS |      | INCHES    |       |
|-----|-------------|------|-----------|-------|
|     | MIN         | MAX  | MIN       | MAX   |
| A   | 4.90        | 5.10 | 0.193     | 0.200 |
| B   | 4.30        | 4.50 | 0.169     | 0.177 |
| C   | ---         | 1.20 | ---       | 0.047 |
| D   | 0.05        | 0.15 | 0.002     | 0.006 |
| F   | 0.50        | 0.75 | 0.020     | 0.030 |
| G   | 0.65 BSC    |      | 0.026 BSC |       |
| H   | 0.50        | 0.60 | 0.020     | 0.024 |
| J   | 0.09        | 0.20 | 0.004     | 0.008 |
| J1  | 0.09        | 0.16 | 0.004     | 0.006 |
| K   | 0.19        | 0.30 | 0.007     | 0.012 |
| K1  | 0.19        | 0.25 | 0.007     | 0.010 |
| L   | 6.40 BSC    |      | 0.252 BSC |       |
| M   | 0°          | 8°   | 0°        | 8°    |

### SOLDERING FOOTPRINT\*

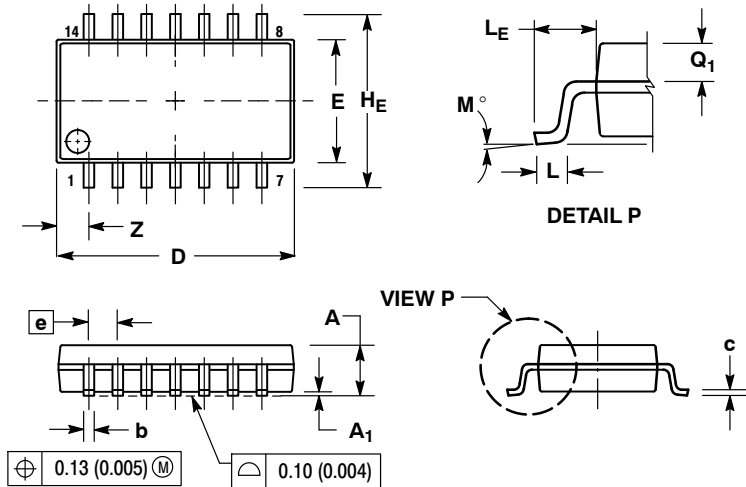


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC74HCT86A

## PACKAGE DIMENSIONS

SOEIAJ-14  
CASE 965-01  
ISSUE B



### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

| DIM            | MILLIMETERS |       | INCHES    |       |
|----------------|-------------|-------|-----------|-------|
|                | MIN         | MAX   | MIN       | MAX   |
| A              | ---         | 2.05  | ---       | 0.081 |
| A <sub>1</sub> | 0.05        | 0.20  | 0.002     | 0.008 |
| b              | 0.35        | 0.50  | 0.014     | 0.020 |
| c              | 0.10        | 0.20  | 0.004     | 0.008 |
| D              | 9.90        | 10.50 | 0.390     | 0.413 |
| E              | 5.10        | 5.45  | 0.201     | 0.215 |
| e              | 1.27 BSC    |       | 0.050 BSC |       |
| H <sub>E</sub> | 7.40        | 8.20  | 0.291     | 0.323 |
| L              | 0.50        | 0.85  | 0.020     | 0.033 |
| L <sub>E</sub> | 1.10        | 1.50  | 0.043     | 0.059 |
| M              | 0°          | 10°   | 0°        | 10°   |
| Q <sub>1</sub> | 0.70        | 0.90  | 0.028     | 0.035 |
| Z              | ---         | 1.42  | ---       | 0.056 |

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MC74HCT86A/D



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